



VMDSEMI

VUSB002R940PA

Datasheet

General Description

VUSB002R940PA MOSFET is based on unique device design to achieve low $R_{DS(ON)}$.

Symbol

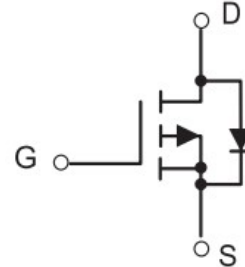
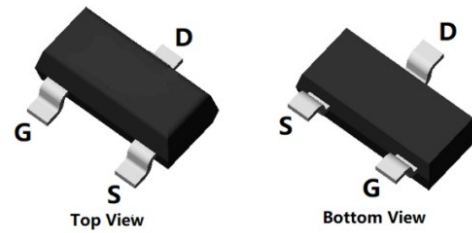


Figure 1 Symbol of VUSB002R940PA

Features

- $R_{DS(ON)_{max}} = 94.0m\Omega @ V_{GS} = -4.5V$
- $R_{DS(ON)_{max}} = 127m\Omega @ V_{GS} = -2.5V$
- Trench Power LV MOSFET technology
- High Density Cell Design for Low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Meets UL 94 V-0 Flammability Rating

Package Type



SOT-23

Figure 2 Package Type of VUSB002R940PA

Application

- Video Monitor
- Power Management

Ordering Information

Product Name	Package
VUSB002R940PA	SOT-23

Absolute Maximum Ratings ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	± 10	V
Continuous Drain Current $T_A = 25^\circ\text{C}@$ Steady state	I_D	-2	A
Continuous Drain Current $T_A = 70^\circ\text{C}@$ Steady state		-1.6	A
Pulsed Drain Current ^{Note1}	I_{DM}	-8	A
Total Power Dissipation $T_A = 25^\circ\text{C}$	P_D	0.7	W
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note2}	$R_{\theta JA}$		178		$^\circ\text{C}/\text{W}$

Notes :

1. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.
2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D = -250\mu A$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20V, V_{GS}=0V$ $T_C = 25\text{ }^\circ\text{C}$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D = -250\mu A$	-0.4	-0.62	-1.0	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -1.5A$		81	94	mΩ
		$V_{GS} = -2.5V, I_D = -1.5A$		109	127	
		$V_{GS} = -1.8V, I_D = -1.5A$		183	215	
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS} = -10V$		327		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		62		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		55		pF
Switching Parameters						
Gate to Source Charge	Q_{gs}	$V_{DS} = -10V$		0.85		nC
Gate to Drain Charge	Q_{gd}	$V_{GS} = -4.5V$		1.4		
Gate Charge Total	Q_g	$I_D = -2A$		4.5		
Reverse Recovery Charge	Q_{rr}	$I_F = -2A$		2.3		ns
Reverse Recovery Time	t_{rr}	$di/dt = -100A/\mu s$		27		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -10V$		6		
Turn-on Rise Time	t_r	$V_{GS} = -4.5V$		30		
Turn-off Delay Time	$t_{d(off)}$	$I_D = -1A$		45		
Turn-off Fall Time	t_f	$R_{GEN} = 2.5\Omega$		46		
Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S = -2A$		-0.8	-1.2	V
Maximum Body-Diode Continuous Current	I_S				-2	A

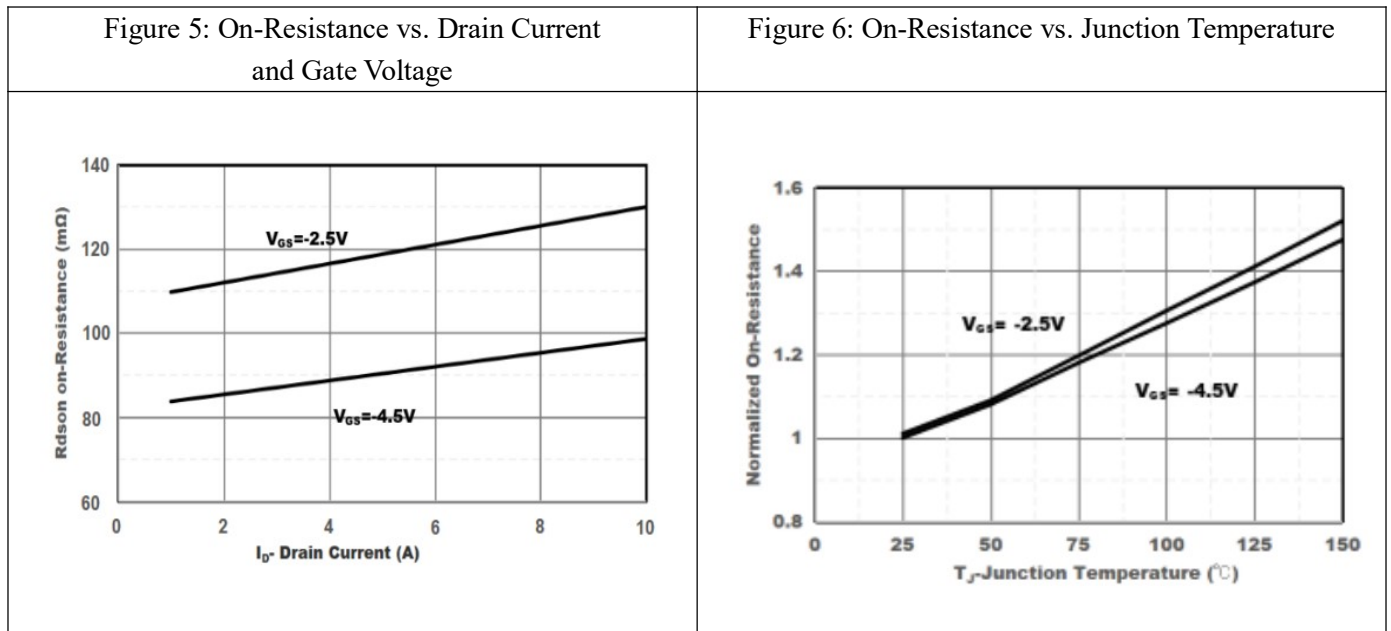
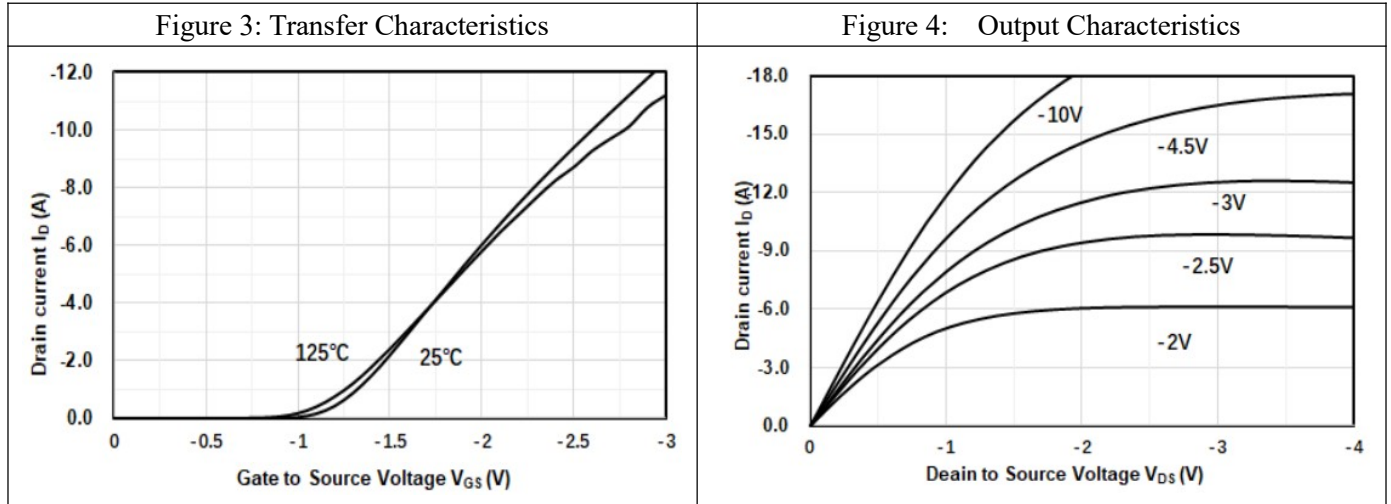
Typical Performance Characteristics


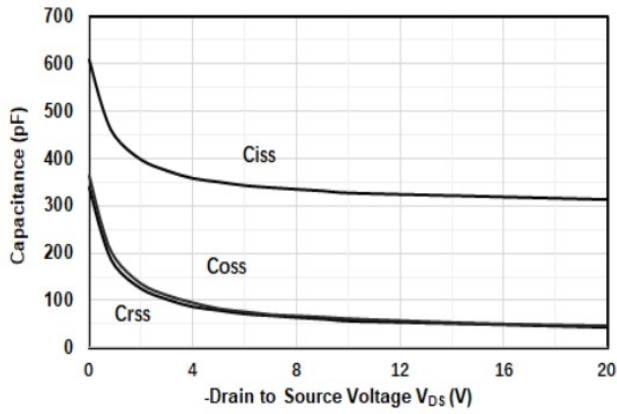
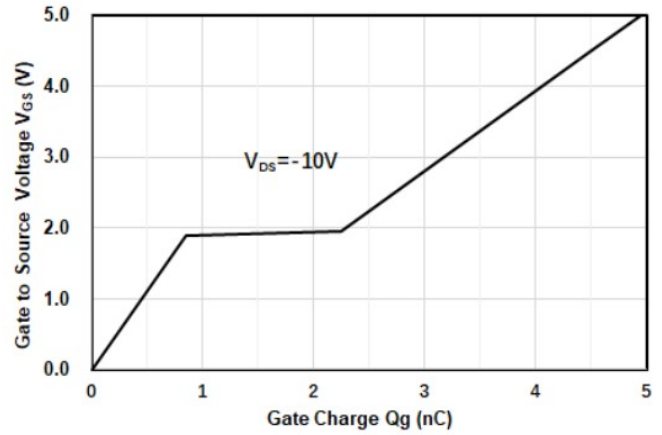
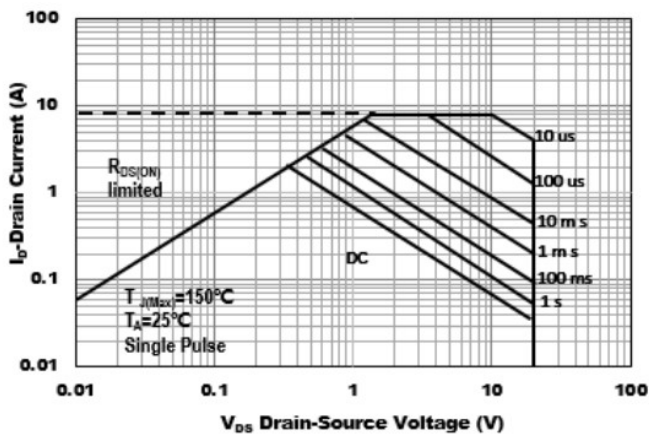
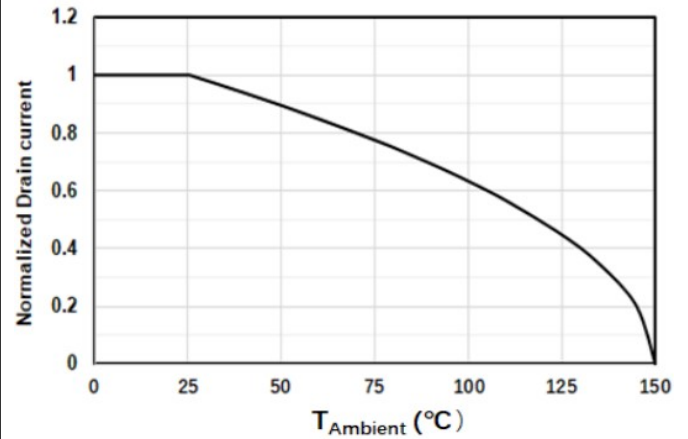
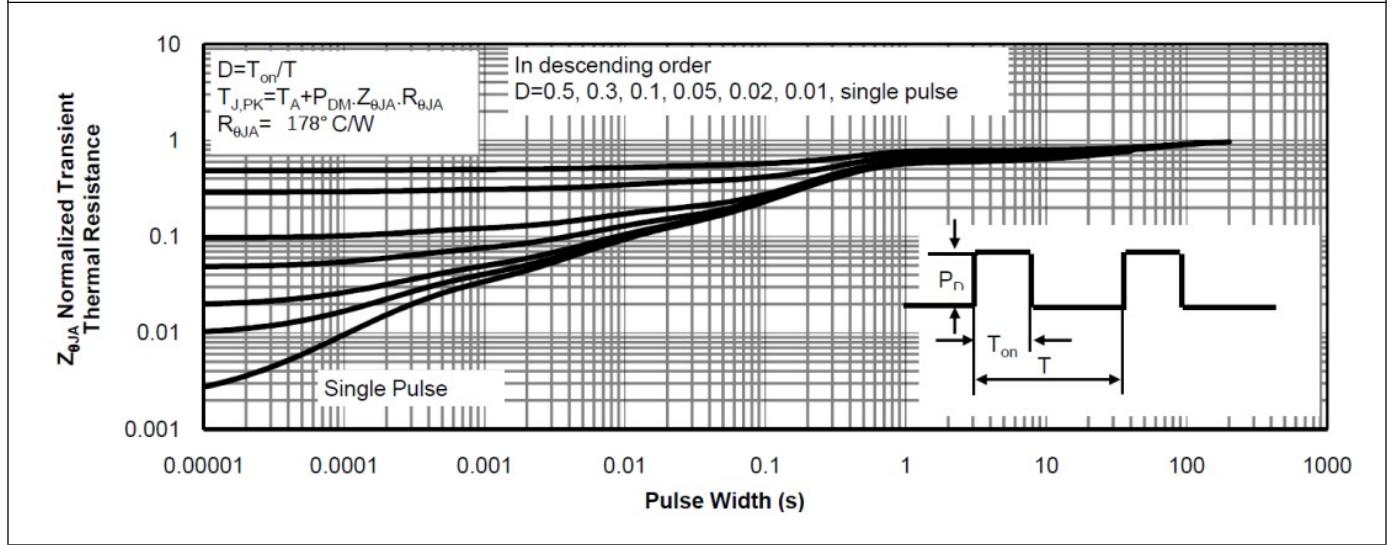
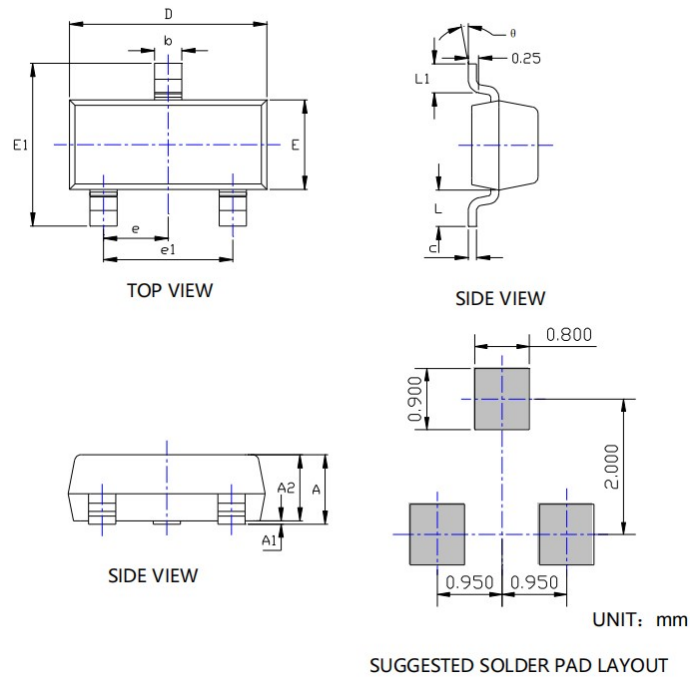
Figure 7: Capacitance Characteristics

Figure 8: Gate Charge

Figure 9: Safe Operation Area

Figure 10: Drain Current vs Ambient temperature


Figure 11: Normalized Maximum Transient Thermal Impedance



Mechanical Dimensions:
SOT-23 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.150	1.500	0.045	0.059
E1	2.250	2.650	0.089	0.104
e	0.950REF		0.037REF	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Note:

1. Package body sizes exclude mode flash and gate burrs.
2. Tolerance 0.1mm unless otherwise specified.
3. The pad layout is for reference purposes only.

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